Abstracts

Optimized flip-chip interconnect for 38 GHz thin-film microstrip multichip modules

Ngoc-Hoa Huynh, W. Heinrich, K. Hirche, W. Scholz, M. Warth and W. Ehrlinger. "Optimized flip-chip interconnect for 38 GHz thin-film microstrip multichip modules." 2000 MTT-S International Microwave Symposium Digest 00.1 (2000 Vol. I [MWSYM]): 69-72.

Flip-chip interconnects with 80 /spl mu/m bumps are optimized for 38 GHz by means of electromagnetic simulation. Thin-film microstrip is used as transmission-line on the carrier substrate. A compensation structure reduces reflections at the interconnect below -20 dB. Measurements of a passive structure and active chip modules proved the feasibility of this approach.

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